

# BIPOLAR ANALOG INTEGRATED CIRCUIT $\mu PC1093$

## ADJUSTABLE PRECISION SHUNT REGULATORS

## **DESCRIPTION**

The  $\mu$ PC1093 are adjustable precision shunt regulators with guaranteed thermal stability. The output voltage can be set to any value between reference voltage (2.495 V) and 36 V by two external resistors.

These ICs can apply to error amplifier of switching regulators.

## **FEATURES**

•	High Accuracy	VREF = 2.495 V $\pm$ 2 %
•	Low Temperature Coefficient	$\Delta V_{REF}/\Delta T \le 100 \text{ ppm/}^{\circ}C$
•	Adjustable Output Voltage by two External Resistors	$V_{REF} \leq V_O \leq 36~V$
•	Low Dynamic Impedance	$ Z_{KA}  = 0.1 \Omega TYP.$

## **ORDERING INFORMATION**

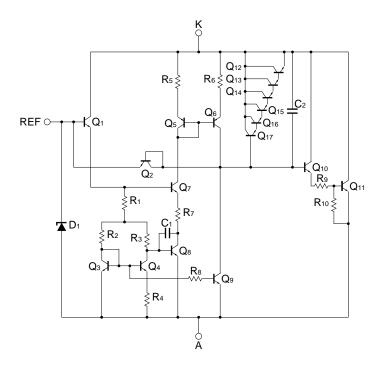
Part Number	Package
μPC1093J	3-pin plastic SIP (TO-92)
$\mu$ PC1093G	8-pin plastic SOP (225 mil)
$\mu$ PC1093T	Power mini mold (SOT-89)
$\mu$ PC1093TA	5-pin plastic mini mold (SC-74A)

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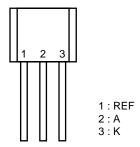
## **EQUIVALENT CIRCUIT**



# PIN CONFIGURATION (Marking Side)

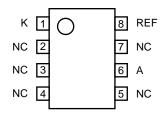
3-pin plastic SIP (TO-92)

• μPC1093J



8-pin plastic SOP (225 mil)

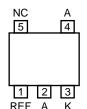
• μPC1093G



- ★ Power mini mold (SOT-89)
  - μPC1093T



- ★ 5-pin plastic mini mold (SC-74A)
  - $\mu$ PC1093TA



REF : Reference A : Anode K : Cathode

NC : No Connection



# ABSOLUTE MAXIMUM RATING (TA = 25 °C, unless otherwise specified.)

Parame	ter	Symbol	Ratings	Unit
Cathode Voltage		Vka	37	V
Cathode Current		lκ	150	mA
Cathode-Anode Reve	erse Current	-Ік	-100	mA
Reference Voltage		VREF	7	V
Reference Input Curi	Reference Input Current		50	μΑ
Reference-Anode Reverse Current		-I <sub>REF</sub>	-10	mA
Power Dissipation	μPC1093J	Рт	700	mW
	μPC1093G		480	
	μPC1093T	]	400/2 000 <sup>Note 1</sup>	
	μPC1093TA	]	180/510 <sup>Note 2</sup>	
Operating Ambient Temperature		TA	-20 ~ +85	°C
Storage Temperature		T <sub>stg</sub>	−65 ~ +150	°C

**Notes 1.** with  $16 \text{ cm}^2 \times 0.7 \text{ mm}$  ceramic substrate

2. with 75 mm $^2 \times 0.7$  mm ceramic substrate

Caution Exposure to Absolute Maximum Ratings for extended periods may affect device reliability; exceeding the ratings could cause permanent damage. The parameters apply independently. The device should be operated within the limits specified under DC and AC Characteristics.

## RECOMMENDED OPERATING CONDITIONS

Parameter		Symbol	MIN.	TYP.	MAX.	Unit
Cathode Voltage		VKA	Vref	5	36	V
Cathode Current		lκ	1	10	100	mA
Power Dissipation	μPC1093J	Рт		50	220	mW
	μPC1093G			50	150	
	μPC1093T			50	125/640 <sup>Note 1</sup>	
	μPC1093TA			50	58/160 <sup>Note 2</sup>	
Operating Ambient Te	emperature	TA	-20		+85	°C

Notes 1. with 16  $\text{cm}^2 \times 0.7$  mm ceramic substrate

2. with 75 mm<sup>2</sup>  $\times$  0.7 mm ceramic substrate

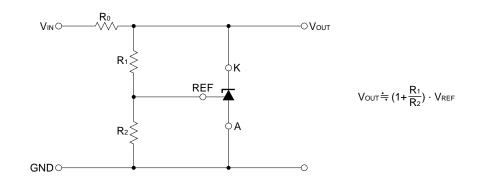
\* \* \*



# ELECTRICAL CHARACTERISTICS (Ta = 25 $^{\circ}$ C, I $\kappa$ = 10 mA, unless otherwise specified.)

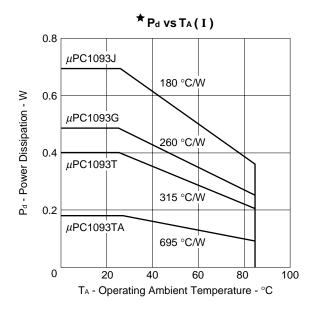
Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Reference Voltage	VREF	VKA = VREF	2.440	2.495	2.550	V
Reference Voltage Deviation Over Temperature	$\Delta V_REF$	0 °C ≤ Ta ≤ 70 °C, Vka = Vref		7	17	mV
Reference Voltage Deviation Over	$\Delta V_{REF}/\Delta V$	VREF   ≤ VKA ≤ 10 V		1.2	2.7	mV/V
Cathode Voltage		10 V ≤ VKA ≤ 36 V		0.7	2	mV/V
Reference Input Current	IREF	$V_{KA}=V_{REF},\;R_{1}=10\;k\Omega,\;R_{2}=\infty$		1	4	μΑ
Reference Input Current Deviation Over Temperature	$\Delta I$ ref	$0~^{\circ}C \leq T_{A} \leq 70~^{\circ}C,~V_{KA} = V_{REF},$ $R_{1} = 10~k\Omega,~R_{2} = \infty$		0.4	1.2	μΑ
Minimum Cathode Current	K min.	Vka = Vref, ΔVref = 2 %		0.4	1	mA
Off-state Cathode Current	K off	VKA = 36 V, VREF = 0		0.1	1	μΑ
Dynamic Impedance	ZKA	$V_{KA} = V_{REF}, f \le 1 \text{ kHz}$ $1 \text{ mA} \le I_K \le 100 \text{ mA}$		0.1	0.5	Ω

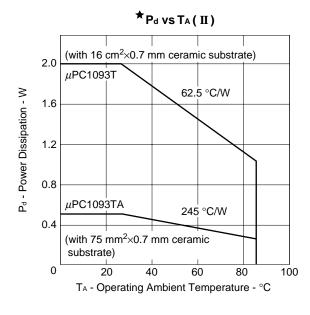
# **TEST AND APPLICATION CIRCUIT**

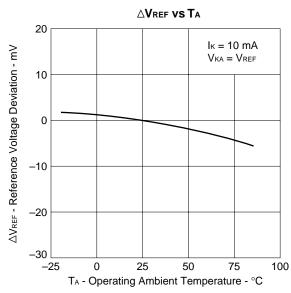


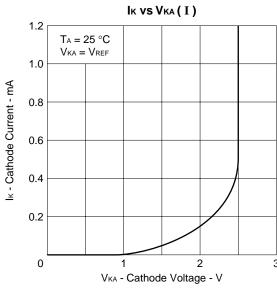


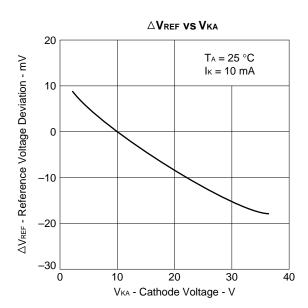
## **TYPICAL CHARACTERISTICS**

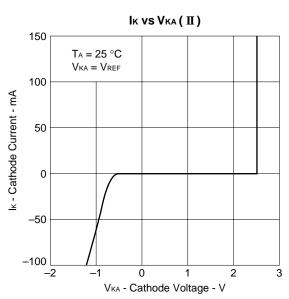


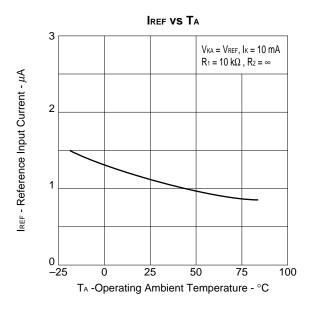


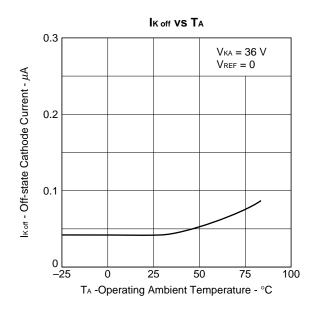


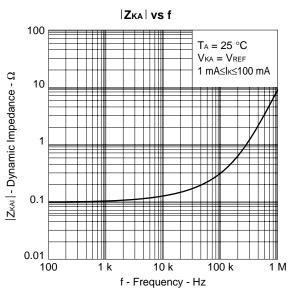


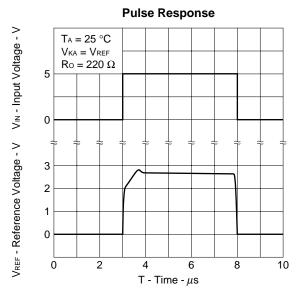


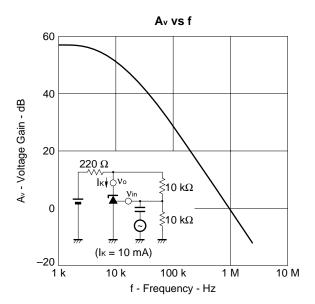


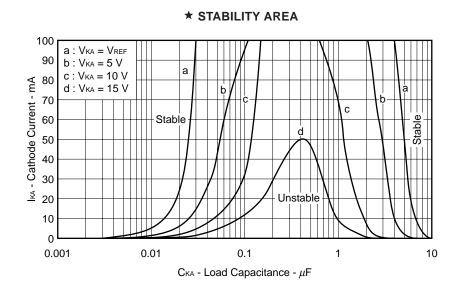




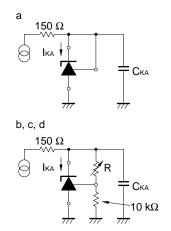








## \* TEST CIRCUIT



**CKA**: Monolithic Ceramic Capacitors

## ★ Caution of Stability Area

If the Aluminum electrolytic capacitor is used, it should be kept CkA  $\geq$  2.2  $\mu$ F.

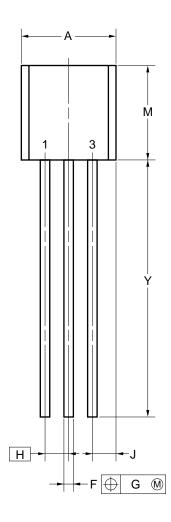
When using plural different types of capacitors, each capacitor is needed to be stable independently.

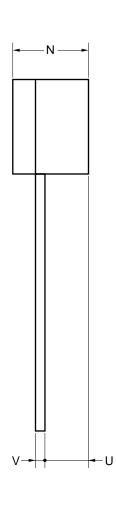
When designing a circuit, take the characteristic variation among devices into consideration, so that the designed circuit has an enough characteristic margin supporting the standard specifications described above.



## **PACKAGE DRAWINGS**

# 3 PIN PLASTIC SIP (TO-92)





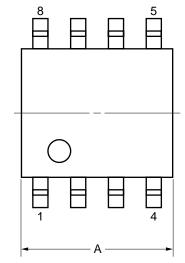
## NOTE

Each lead centerline is located within 0.12 mm of its true position (T.P.) at maximum material condition.

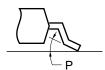
ITEM	MILLIMETERS
Α	5.0±0.2
F	$0.5^{+0.3}_{-0.1}$
G	0.12
Н	1.27
J	1.33 MAX.
М	5.0±0.5
N	4.0±0.2
U	2.8 MAX.
V	0.5±0.1
Υ	15.0±0.7

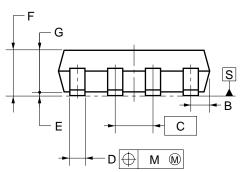
P3J-127B-2

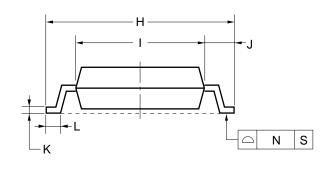
# 8 PIN PLASTIC SOP (225 mil)



detail of lead end







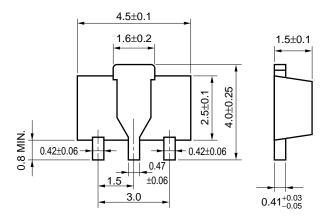
## NOTE

Each lead centerline is located within 0.12 mm of its true position (T.P.) at maximum material condition.

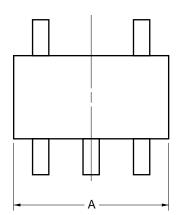
ITEM	MILLIMETERS
Α	$5.2^{+0.17}_{-0.20}$
В	0.78 MAX.
С	1.27 (T.P.)
D	$0.42^{+0.08}_{-0.07}$
E	0.1±0.1
F	1.59±0.21
G	1.49
Н	6.5±0.3
ı	4.4±0.15
J	1.1±0.2
K	$0.17^{+0.08}_{-0.07}$
L	0.6±0.2
М	0.12
N	0.10
Р	3°+7°

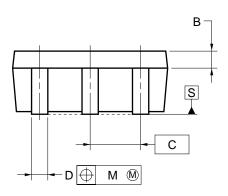
S8GM-50-225B-5

# \* POWER MINI MOLD (SOT-89) (Unit: mm)

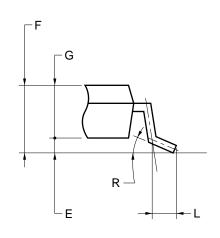


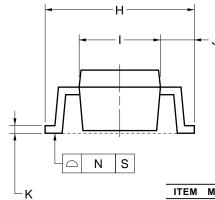
# **★** 5 PIN PLASTIC MINI MOLD





## detail of lead end





ITEM	MILLIMETERS
Α	2.9±0.2
В	0.3
С	0.95 (T.P.)
D	$0.32^{+0.05}_{-0.02}$
E	0.05±0.05
F	1.4 MAX.
G	$1.1^{+0.2}_{-0.1}$
Н	2.8±0.2
1	$1.5^{+0.2}_{-0.1}$
J	$0.65^{+0.1}_{-0.15}$
К	$0.16^{+0.1}_{-0.06}$
L	0.4±0.2
М	0.19
N	0.1
R	5°±5°

S5TA-95-15A



## **★ RECOMMENDED SOLDERING CONDITIONS**

When soldering this product, it is highly recommended to observe the conditions as shown below. If other soldering processes are used, or if the soldering is performed under different conditions, please make sure to consult with our sales offices.

For more details, refer to our document "SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL" (C10535E).

## Through-hole device

 $\mu$ PC1093J: 3-pin plastic SIP (TO-92)

Process	Conditions	
Wave soldering	Solder temperature: 260 °C or below,	
(only to leads)	Flow time: 10 seconds or less.	

Caution For through-hole device, the wave soldering process must be applied only to leads, and make sure that the package body does not get jet soldered.

#### Surface mount devices

 $\mu$ PC1093G: 8-pin plastic SOP (225 mil)

Process	Conditions	Symbol
Infrared ray reflow	Peak temperature: 230 °C or below (Package surface temperature), Reflow time: 30 seconds or less (at 210 °C or higher), Maximum number of reflow processes: 1 time.	IR30-00-1
VPS	Peak temperature: 215 °C or below (Package surface temperature), Reflow time: 40 seconds or less (at 200 °C or higher), Maximum number of reflow processes: 1 time.	VP15-00-1
Wave soldering	Solder temperature: 260 °C or below, Flow time: 10 seconds or less,  Maximum number of flow processes: 1 time,  Pre-heating temperature: 120 °C or below (Package surface temperature).	WS60-00-1

Caution Apply only one kind of soldering condition to a device, or the device will be damaged by heat stress.



## $\mu$ PC1093T: Power mini mold (SOT-89)

Process	Conditions	Symbol
Infrared ray reflow	Peak temperature: 235 °C or below (Package surface temperature), Reflow time: 30 seconds or less (at 210 °C or higher), Maximum number of reflow processes: 2 times.	IR35-00-2
VPS	Peak temperature: 215 °C or below (Package surface temperature), Reflow time: 40 seconds or less (at 200 °C or higher), Maximum number of reflow processes: 2 times.	VP15-00-2
Wave soldering	Solder temperature: 260 °C or below, Flow time: 10 seconds or less,  Maximum number of flow processes: 1 time,  Pre-heating temperature: 120 °C or below (Package surface temperature).	WS60-00-1

Caution Apply only one kind of soldering condition to a device, or the device will be damaged by heat stress.

 $\mu$ PC1093TA: 5-pin plastic mini mold (SC-74A)

Process	Conditions	Symbol
Infrared ray reflow	Peak temperature: 235 °C or below (Package surface temperature), Reflow time: 30 seconds or less (at 210 °C or higher), Maximum number of reflow processes: 3 times.	IR35-00-3
VPS	Peak temperature: 215 °C or below (Package surface temperature), Reflow time: 40 seconds or less (at 200 °C or higher), Maximum number of reflow processes: 3 times.	VP15-00-3
Wave soldering	Solder temperature: 260 °C or below, Flow time: 10 seconds or less,  Maximum number of flow processes: 1 time,  Pre-heating temperature: 120 °C or below (Package surface temperature).	WS60-00-1

Caution Apply only one kind of soldering condition to a device, or the device will be damaged by heat stress.



## **★ REFERENCE DOCUMENTS**

C11531E
C10535E
C10943X
X10679E
IEI-1212

<sup>-</sup>Three Terminal Regulator

## \* REMARK OF THE PACKAGE MARK

The package marks of the  $\mu PC1093T$  and the  $\mu PC1093TA$  are the symbols as follows.

Part Number	Mark
μPC1093T	93
μPC1093TA	K93

NEC  $\mu$ PC1093

[MEMO]

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The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

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Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots

Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)

Specific: Aircrafts, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

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Anti-radioactive design is not implemented in this product.

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